PATENT ASSIGNMENT

Electronic Version v08
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT OF ASSIGNOR'S INTEREST

CONVEYING PARTY DATA

Name	Execution Date
Takashi OZAKI	2005-05-10
Tomoshi TANIYAMA	2005-03-29
Hiroshi UNAMI	2005-03-29
Kiyohiko MAEDA	2005-03-29
Shinya MORITA	2005-03-17
Yoshikazu TAKASHIMA	2005-03-17
Sadao HISAKADO	2005-03-30

RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
HITACHI KOKUSAI ELECTRIC INC.	14-20, Higashi-Nakano 3-chome, Nakano-ku,		Tokyo	JAPAN	164-8511

CH $40.00 012340 10528137

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number	10528137

CORRESPONDENCE DATA

FAX NUMBER: 2028870357
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 023850

NAME OF PERSON SIGNING:	William L. Brooks
DATE SIGNED:	2005-12-12

Total Attachments: 2
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U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's Name(s) Address(es))

HITACHI KOKUSAI ELECTRIC INC. of 14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled:

(Title of Invention)

SUBSTRATE PROCESSING APPARATUS AND METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

(*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on March 17, 2005, Serial No. 10/528,137.

(**Armstrong, Kratz, Quintos, Hanson & Brooks, LLP** is hereby authorized to insert the serial code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

T. Ozaki (Signature)	**Takashi OZAKI** (Type Name)	May, 10, 2005 (Date)
T. Taniyama (Signature)	**Tomoshi TANIYAMA** (Type Name)	March 29 2005 (Date)
H. Unami (Signature)	**Hiroshi UNAMI** (Type Name)	March 29, 2005 (Date)
K. Maeda (Signature)	**Kiyohiko MAEDA** (Type Name)	March 29, 2005 (Date)
S. Morita (Signature)	**Shinya MORITA** (Type Name)	March 17, 2005 (Date)
Y. Takashima (Signature)	**Yoshikazu TAKASHIMA** (Type Name)	March 17, 2005 (Date)

NO LEGALIZATION REQUIRED Re. 01/04

Docket No. 050161 Armstrong, Kratz, Quintos, Hanson & Brooks, LLP

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IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

S. Hisakado	**Sadao HISAKADO**	March. 30, 2005
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)

NO LEGALIZATION REQUIRED Re. 01/04